



PRODUCT DATASHEET



- PLCC4 SMD
- ▶ 3528 Series
- Red / Green / Blue



RÓHS Compliant





- Package: PLCC4 RGB Black Surface SMD Package
- Forward Current: 20/20/20mA
- Forward Voltage (typ.): 1.9/3.2/3.2V •
- Luminous Flux (typ.): 700/1450/280mcd @20mA •
- Colour: Red/Green/Blue •
- CCT/Wavelength: 625/530/470nm
- Viewing angle: 120/120/120° •
- Materials:
 - Die: AlGaInP/InGaN/InGaN _
 - Resin: Eploxy (White Diffused)
- Operating Temperature: -40~+80°C .
- Storage Temperature: -40~+100°C
- ESD: 1000V (HBM) .
- **Grouping parameters:**
 - Forward voltage
 - Luminous intensity _
 - _ Wavelength
- Soldering methods: IR Reflow soldering
- Preconditioning: MSL 3 according to JEDEC
- Packing: 8mm tape with 2000pcs/reel, ø180mm (7")

NOM03S71BS



APPLICATIONS:

- LED Display •
- Switch Light
- **3C** Application •
- **Decoration Lighting** .
- **Light Strip**



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	50/30/30*	mA
Pulse Forward Current (duty 1/10; width 0.1ms)	I _{MAX}	80/80/80	mA
Power Dissipation	P _D	100/80/80	mW
Reverse Voltage	V _R	-5	V
Reverse Current @5V	I _R	10	μΑ
Electrostatic Discharge (HBM)	ESD	1000	V
Junction Temperature	Tj	110	°C
Soldering Temperature	T _{sol}	260	°C
Operating Temperature	T _{OPR}	-40~+80	°C
Storage Temperature	T _{STG}	-40~+100	°C

1. * In the order of Red/Green/Blue.



		Values			Test	
Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Red - Forward Voltage	V _F	1.8	1.9	2.6	V	I _F =20mA
Red - Luminous Intensity	I _V	510	700	1000	mcd	I _F =20mA
Red - Wavelength	W _P	615		630	nm	I _F =20mA
Green - Forward Voltage	V _F	2.8	3.2	3.8	V	I _F =20mA
Green - Luminous Intensity	Iv	1080	1450	2125	mcd	I _F =20mA
Green - Wavelength	W _P	519		534	nm	I _F =20mA
Blue - Forward Voltage	V _F	2.8	3.2	3.8	V	I _F =20mA
Blue - Luminous Intensity	Iv	200	280	395	mcd	I _F =20mA
Blue - Wavelength	W _P	461		476	nm	I _F =20mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =20mA

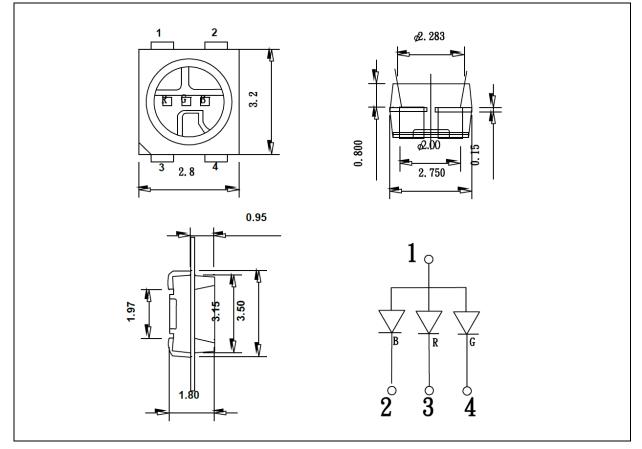
Electrical & Optical Characteristics (Ta=25°C)

1. Luminous intensity (I_V) ±5%, Forward Voltage (V_F) ±0.1V, Viewing angle($2\theta_{1/2}$) ±5%



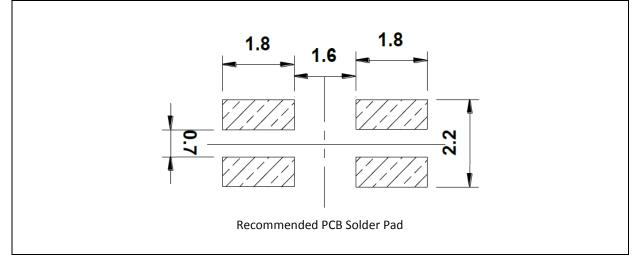


Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ± 0.1 mm with angle tolerance $\pm 0.5^{\circ}$.



BINNING GROUPS:

Code	Min.	Max.	Unit
R1 (Red)	1.8	1.9	
R2 (Red)	1.9	2.0	
R3 (Red)	2.0	2.1	
R4 (Red)	2.1	2.2	
R5 (Red)	2.2	2.3	V
R6 (Red)	2.3	2.4	
R7 (Red)	2.4	2.5	
R8 (Red)	2.5	2.6	
			·
G1 / B1 (Green / Blue)	2.8	2.9	
G2 / B2 (Green / Blue)	2.9	3.0	
G3 / B3 (Green / Blue)	3.0	3.1	
G4 / B4 (Green / Blue)	3.1	3.2	
G5 / B5 (Green / Blue)	3.2	3.3	
G6 / B6 (Green / Blue)	3.3	3.4	V
G7 / B7 (Green / Blue)	3.4	3.5]
G8 / B8 (Green / Blue)	3.5	3.6	1
G9 / B9 (Green / Blue)	3.6	3.7]
G10 / B10 (Green / Blue)	3.7	3.8]

Forward Voltage Classifications (I_F = 20mA):



Luminous Intensity Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
RT12 (Red)	510	645	
RT13 (Red)	645	800	mcd
RT14 (Red)	800	1000	

GT12 (Green)	1080	1350	
GT13 (Green)	1350	1700	mcd
GT14 (Green)	1700	2125	

BT10 (Blue)	200	250	
BT11 (Blue)	250	315	mcd
BT12 (Blue)	315	395	

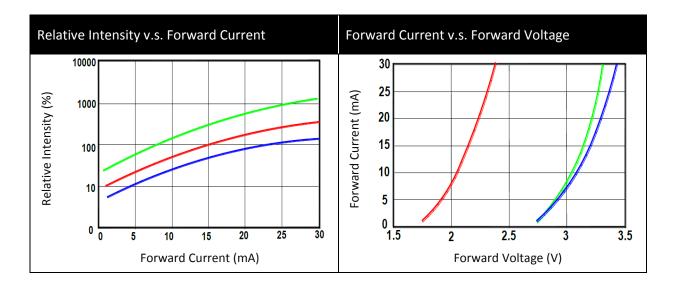
Wavelength Classifications ($I_F = 20mA$):

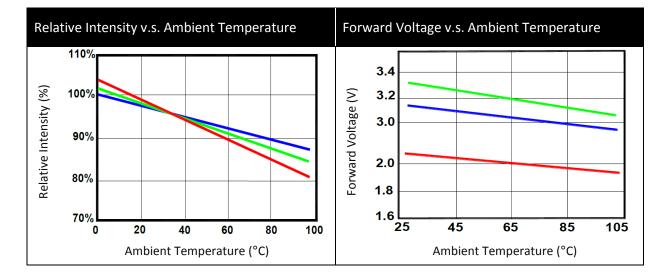
Code	Min.	Max.	Unit
R2 (Red)	615	620	
R3 (Red)	620	625	nm
R4 (Red)	625	630	
		-	
G2 (Green)	519	524	
G3 (Green)	524	529	nm
G4 (Green)	529	534	
B2 (Blue)	461	466	

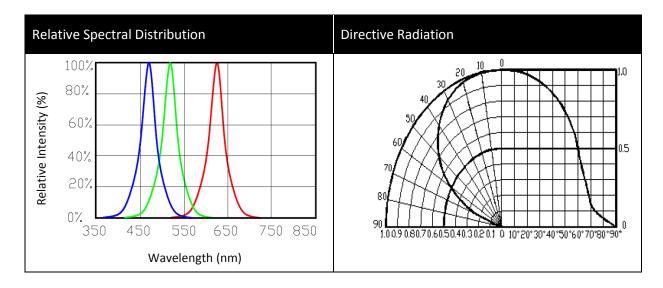
B2 (Blue)	461	466	
B3 (Blue)	466	471	nm
B4 (Blue)	471	476	



ELECTRO-OPTICAL CHARACTERISTICS:

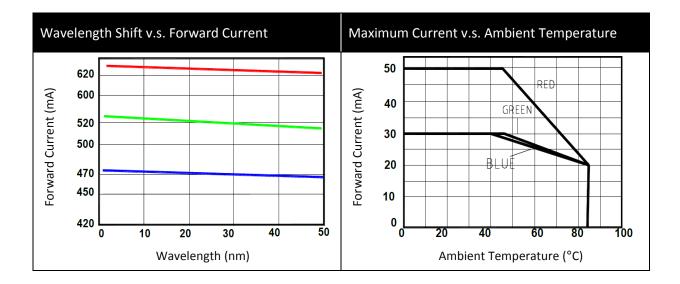








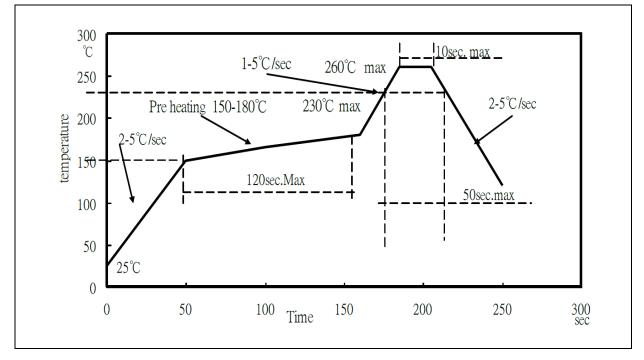
ELECTRO-OPTICAL CHARACTERISTICS:





RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:



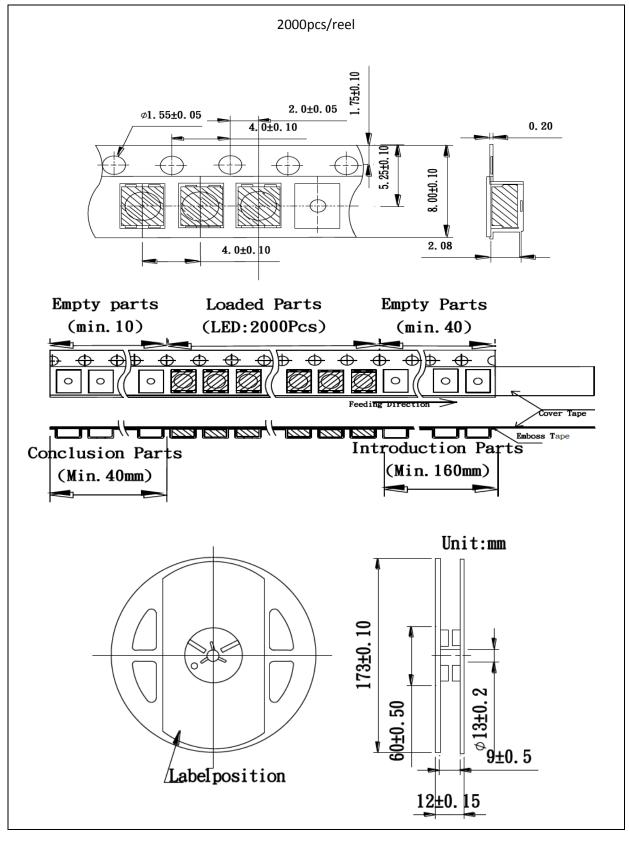
Note:

- 1. Maximum reflow soldering: 3 times.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:



Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	22/09/2014	Datasheet set-up.